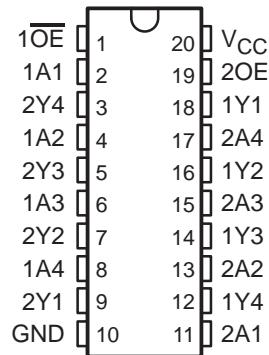


- BiCMOS Design Significantly Reduces I_{CCZ}
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model ($C = 200 \text{ pF}$, $R = 0$)
- High-Impedance State During Power Up and Power Down
- Open-Collector Outputs Drive Bus Lines or Buffer-Memory Address Registers
- Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic and Ceramic 300-mil DIPs (N)

DW OR N PACKAGE
(TOP VIEW)



description

This octal buffer and line driver is designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. The device provides complementary output-enable (OE and \overline{OE}) inputs and noninverting outputs.

The SN64BCT757 is characterized for operation from -40°C to 85°C and 0°C to 70°C .

FUNCTION TABLES

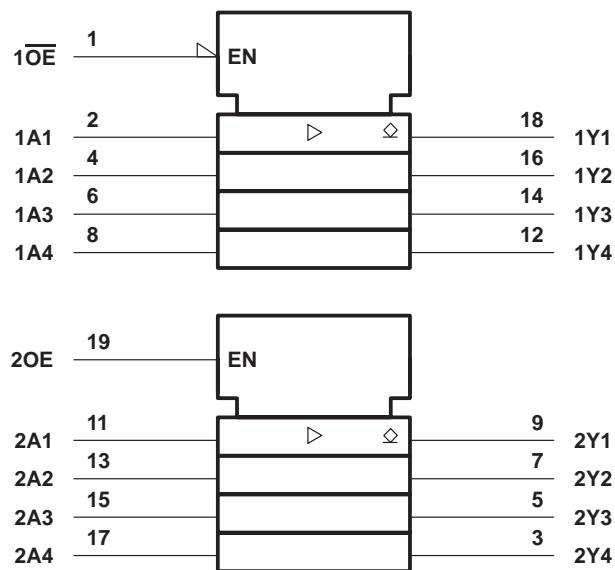
INPUTS		OUTPUT 1Y
1OE	1A	
H	X	H
L	L	L
L	H	H

INPUTS		OUTPUT 2Y
2OE	2A	
L	X	H
H	L	L
H	H	H

SN64BCT757
OCTAL BUFFER/DRIVER
WITH OPEN-COLLECTOR OUTPUTS

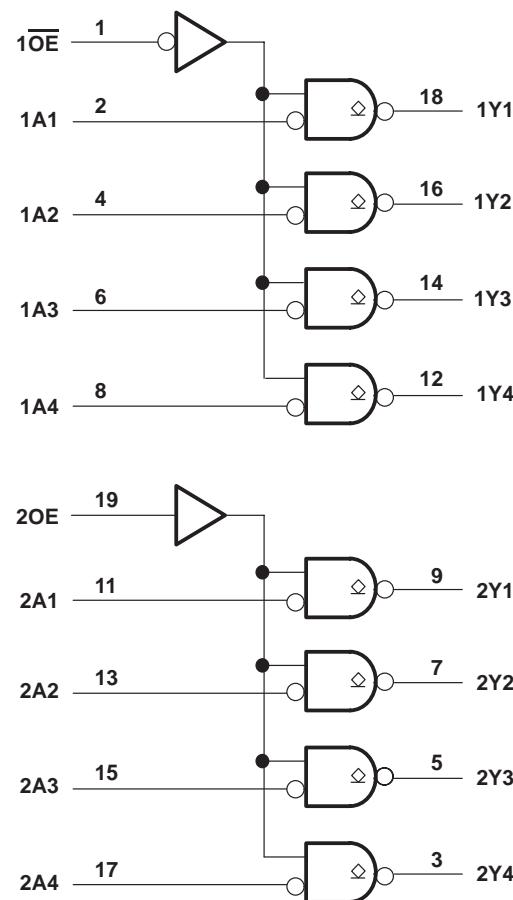
SCBS479 – MARCH 1993 – REVISED MAY 1994

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC}	-0.5 V to 7 V
Input voltage range, V_I (see Note 1)	-0.5 V to 7 V
Voltage range applied to any output in the disabled or power-off state, V_O	-0.5 V to 5.5 V
Voltage range applied to any output in the high state, V_O	-0.5 V to V_{CC}
Input clamp current, I_{IK} ($V_I < 0$)	-30 mA
Current into any output in the low state, I_O	128 mA
Operating free-air temperature range	-40°C to 85°C
Storage temperature range	-65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input negative-voltage ratings may be exceeded if the input clamp-current ratings are observed.

recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage		2		V
V_{IL}	Low-level input voltage			0.8	V
V_{OH}	High-level output voltage			5.5	V
I_{IK}	Input clamp current			-18	mA
I_{OL}	Low-level output current			64	mA
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		2		$\mu s/V$
T_A	Operating free-air temperature	-40		85	$^{\circ}C$

NOTE 2: Unused or floating inputs must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			MIN	TYP†	MAX	UNIT
	$V_{CC} = 4.5$ V,	$I_I = -18$ mA					
I_{OH}	$V_{CC} = 4.5$ V,		$V_{OH} = 5.5$ V			0.1	mA
V_{OL}	$V_{CC} = 4.5$ V,		$I_{OL} = 64$ mA		0.42	0.55	V
I_{OZ}	$V_{CC} = 0$ to 2.3 V (power up),	$V_O = 2.7$ V,	$\overline{OE} = 0.8$ V or $OE = 2$ V			50	μA
I_{OZ}	$V_{CC} = 1.8$ V to 0 (power down),	$V_O = 2.7$ V,	$\overline{OE} = 0.8$ V or $OE = 2$ V			50	μA
I_I	$V_{CC} = 5.5$ V,		$V_I = 7$ V			0.1	mA
I_{IH}	$V_{CC} = 5.5$ V,		$V_I = 2.7$ V			20	μA
I_{IL}	$V_{CC} = 5.5$ V,		$V_I = 0.5$ V			-1	mA
I_{CC}	$V_{CC} = 5.5$ V,	Outputs open	Outputs high			34	mA
			Outputs low			77	
			OE and \overline{OE} inactive			10	
C_I	$V_{CC} = 5$ V,		$V_I = 2.5$ V or 0.5 V			6	pF
C_O	$V_{CC} = 5$ V,		$V_O = 2.5$ V or 0.5 V			4	pF

† All typical values are at $V_{CC} = 5$ V, $T_A = 25^{\circ}C$.

switching characteristics over recommended range of supply voltage, $C_L = 50$ pF (unless otherwise noted) (see Note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5$ V, $T_A = 25^{\circ}C$			$T_A = -40^{\circ}C$ to $85^{\circ}C$		$T_A = 0^{\circ}C$ to $70^{\circ}C$		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	6.9	8.3	9.6	6.5	11.2	6.6	10.1	ns
			2.4	4.2	6	1.9	7	2	6.6	
t_{PHL}	2OE	Y	11	14.8	17.9	10.4	21.3	10.8	19.7	ns
			2.9	4.6	6.2	2.6	7.5	2.6	6.9	
t_{PLH}	1 \overline{OE}	Y	11.4	13.9	16.1	8.9	19.9	10	18	ns
			4.4	6.1	7.8	4	9.2	4	8.5	

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN64BCT757DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN64BCT757DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN64BCT757DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN64BCT757DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN64BCT757DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN64BCT757DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN64BCT757N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN64BCT757NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

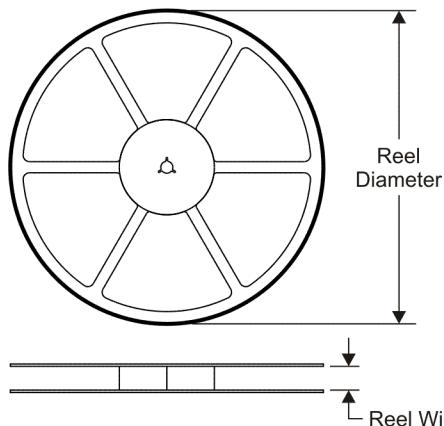
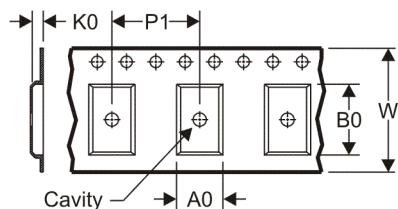
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

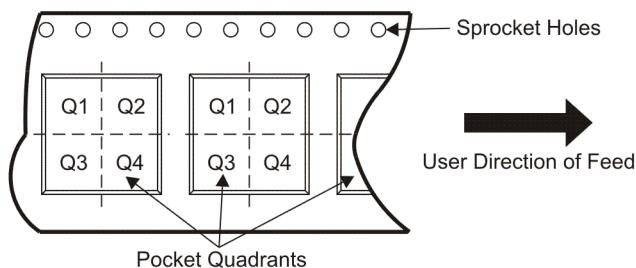
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


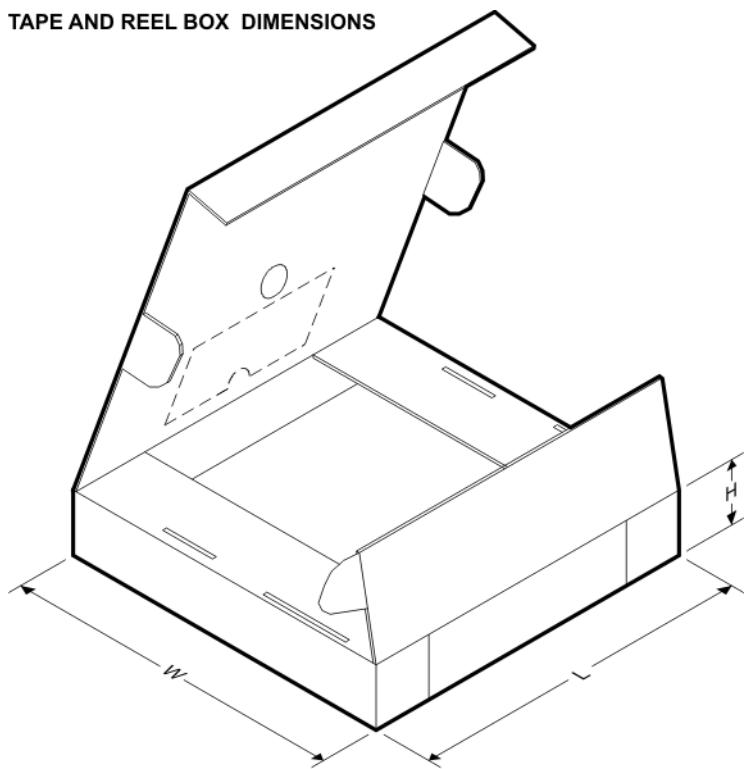
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN64BCT757DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS

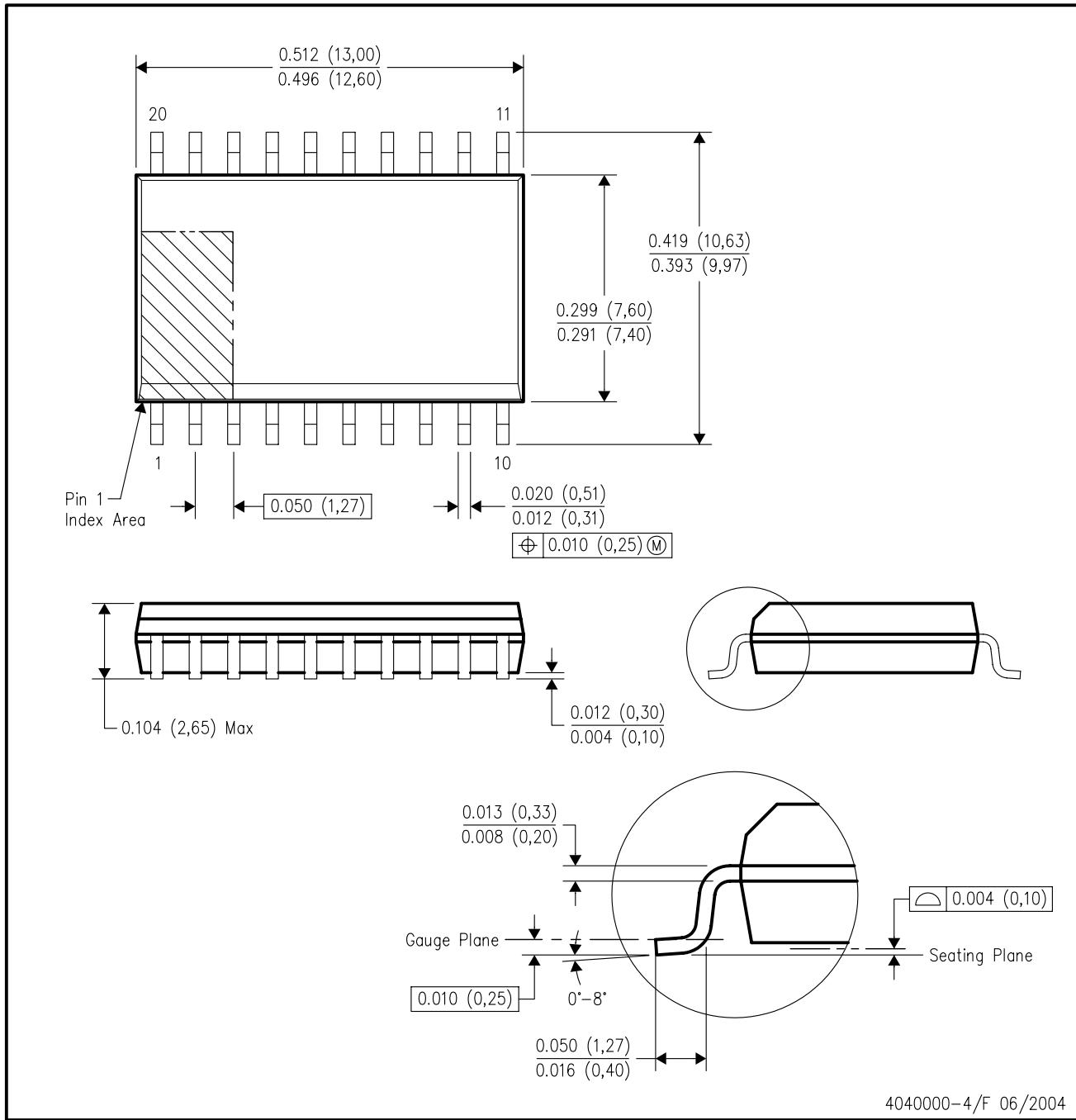


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN64BCT757DWR	SOIC	DW	20	2000	346.0	346.0	41.0

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



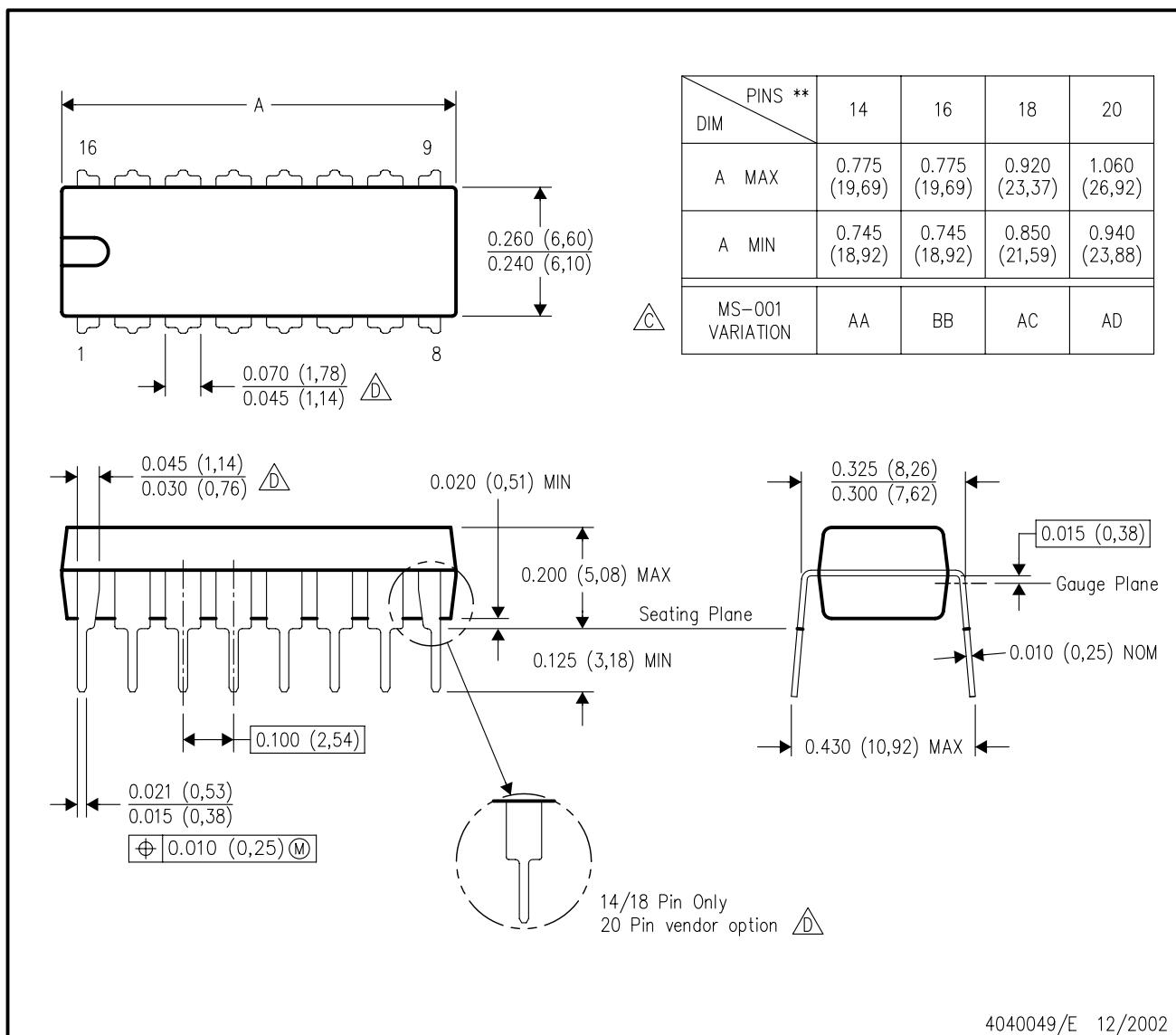
NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- Falls within JEDEC MS-013 variation AC.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.

△ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

△ The 20 pin end lead shoulder width is a vendor option, either half or full width.

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